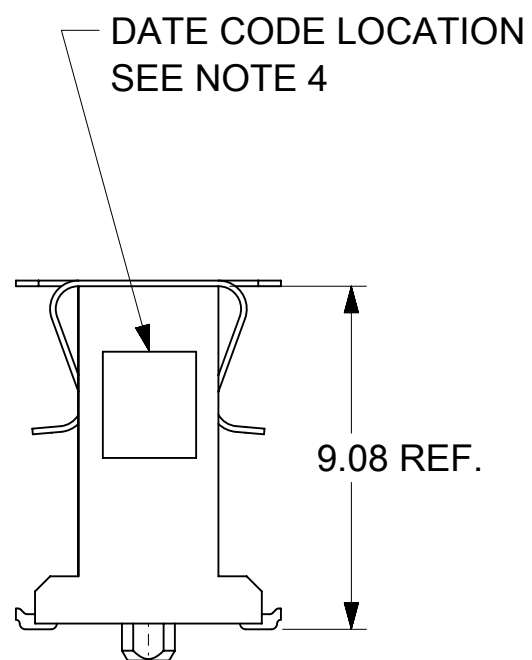
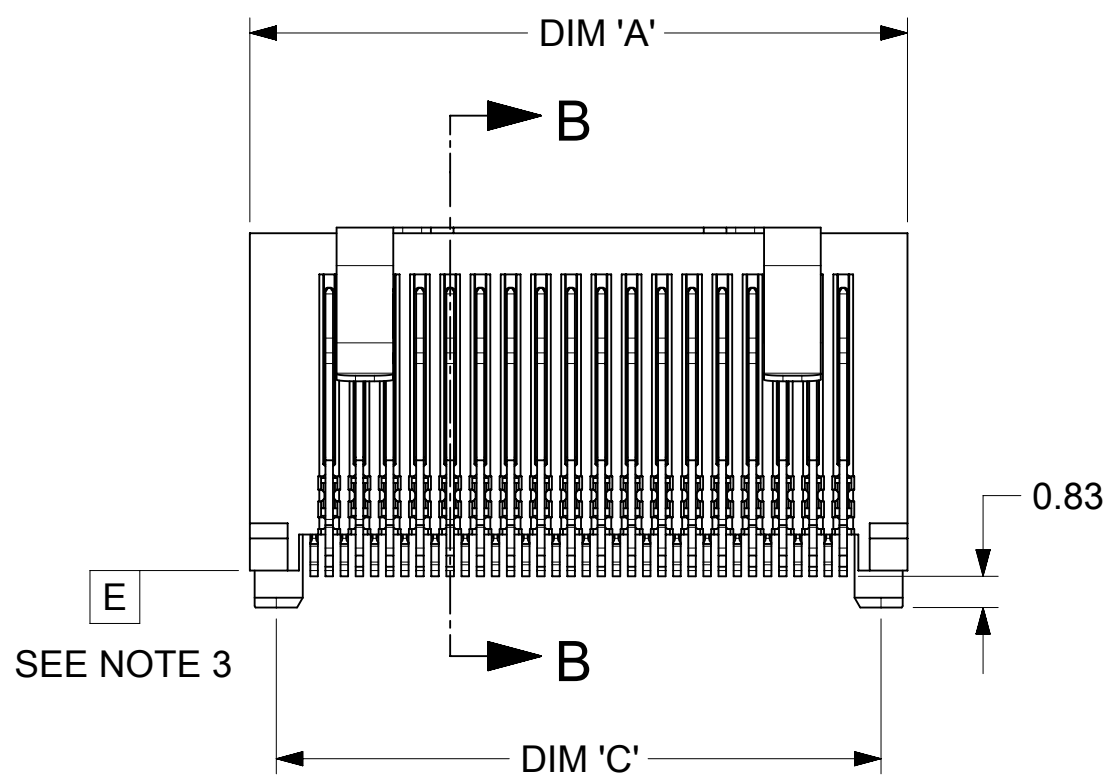
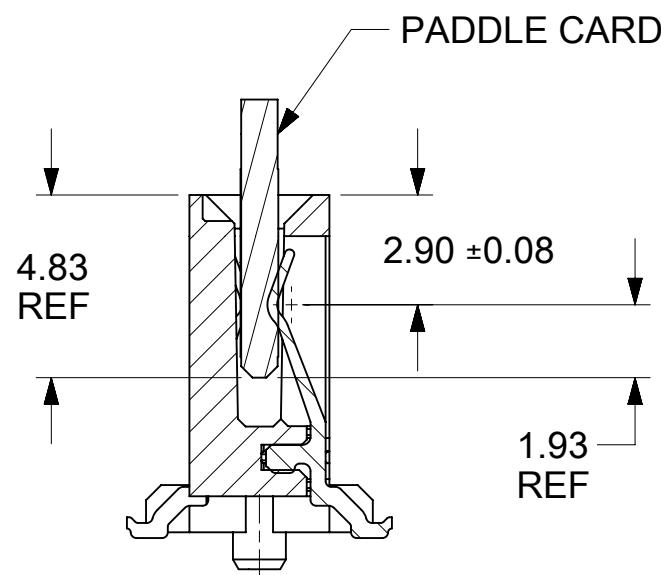
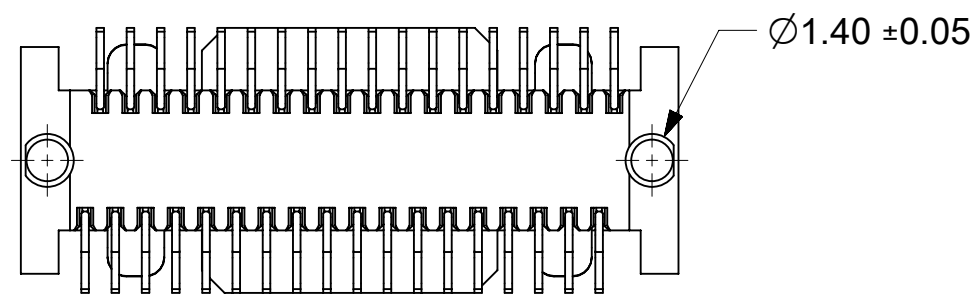


36 CIRCUIT ASSEMBLY SHOWN



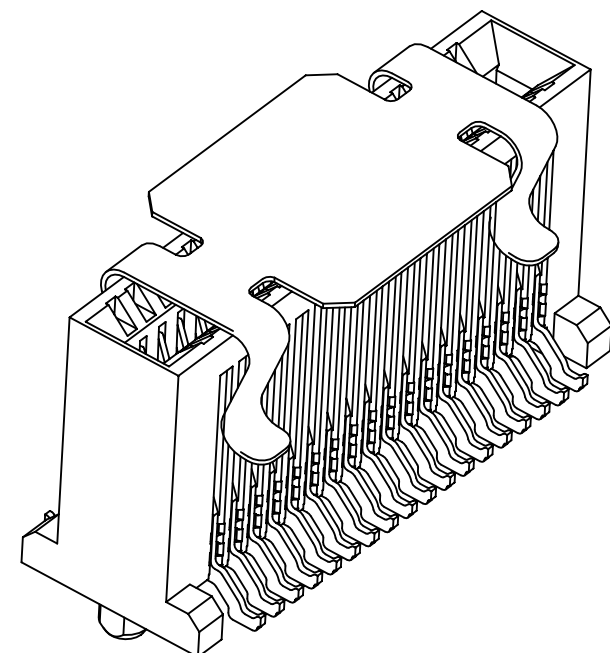
NOTES:

1. MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED, UL 94V-0, BLACK
TERMINALS - COPPER ALLOY
2. TERMINAL PLATING:
OPTION 1
CONTACT AREA: 0.38µm HARD GOLD OVER 2.54µm NICKEL
SOLDER AREA: 2.54-5.09µm TIN OVER 1.27µm NICKEL
OPTION 2
CONTACT AREA: 0.76µm HARD GOLD OVER 2.54µm NICKEL
SOLDER AREA: 2.54-5.09µm TIN OVER 1.27µm NICKEL
3. TERMINAL SOLDER FEET TO BE COPLANAR WITHIN 0.10/.004 MEASURED FROM FRONT HOUSING STANDOFF (DATUM E)
4. DATE CODE: 4 DIGIT (3 DIGIT DAY, 1 DIGIT YEAR)
5. CIRCUIT IDENTIFIER: SEE APPROPRIATE INDUSTRY SPECIFICATION FOR LOCATION OF PIN 1
6. MATES WITH:
A. INTERNAL CABLE SERIES:
79575/74563/79576/74573/79536/74562/74569/74586
B. PADDLE CARD PCB: DO NOT BOTTOM OUT PCB IN THE CONNECTOR. SEE SECTION Z-Z.
- USE WITH APPROPRIATE INTERNAL SHELL FROM SD-76010-002
7. LITTLE ROCK PACKAGING PER PK-75577-001
CHENGDU PACKAGING PER PK-75577-002
8. CONFORMS TO PRODUCT SPECIFICATION PS-75783-001
9. CONFORMS TO APPLICATION SPECIFICATION AS-75783-001



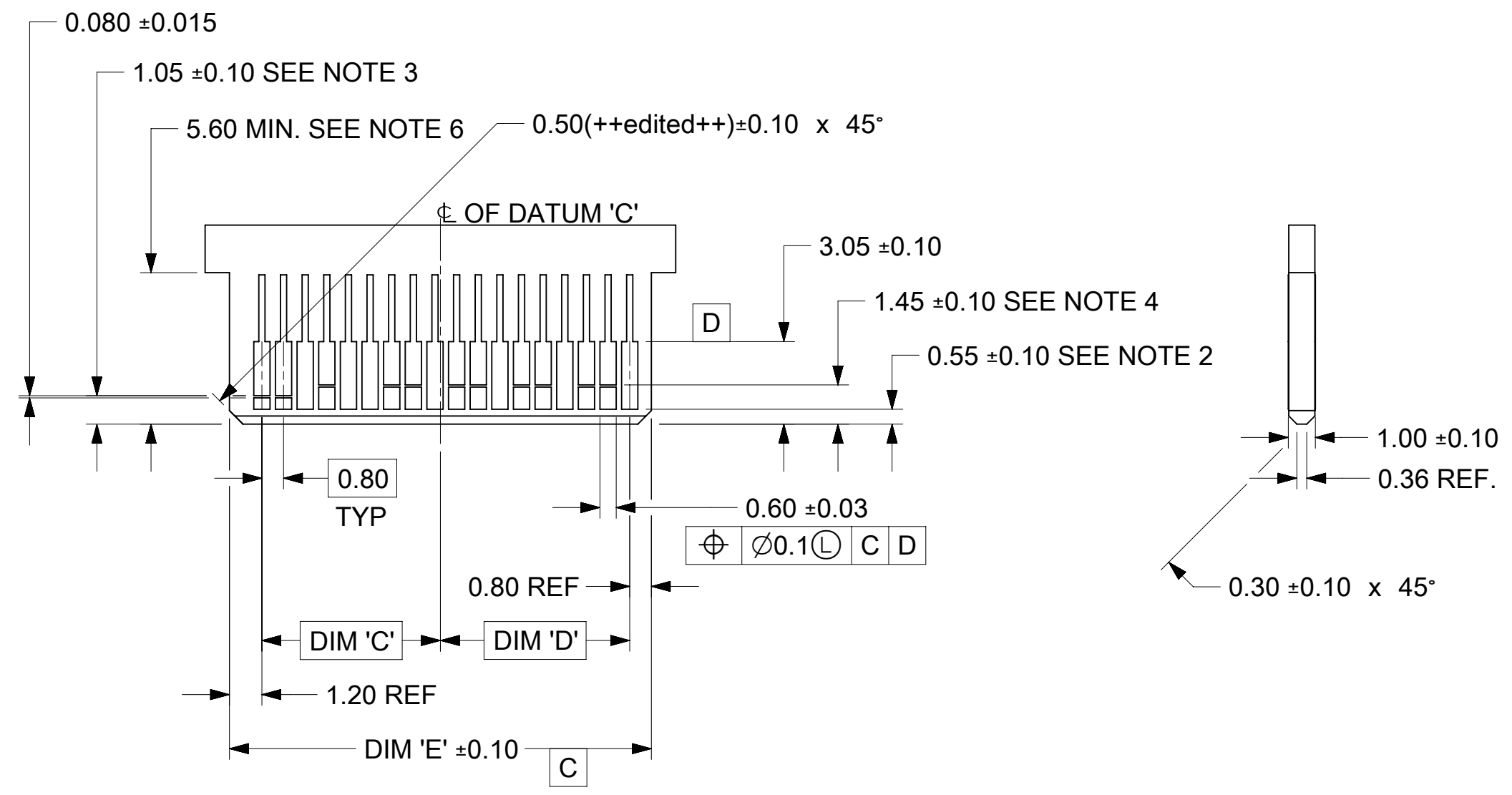
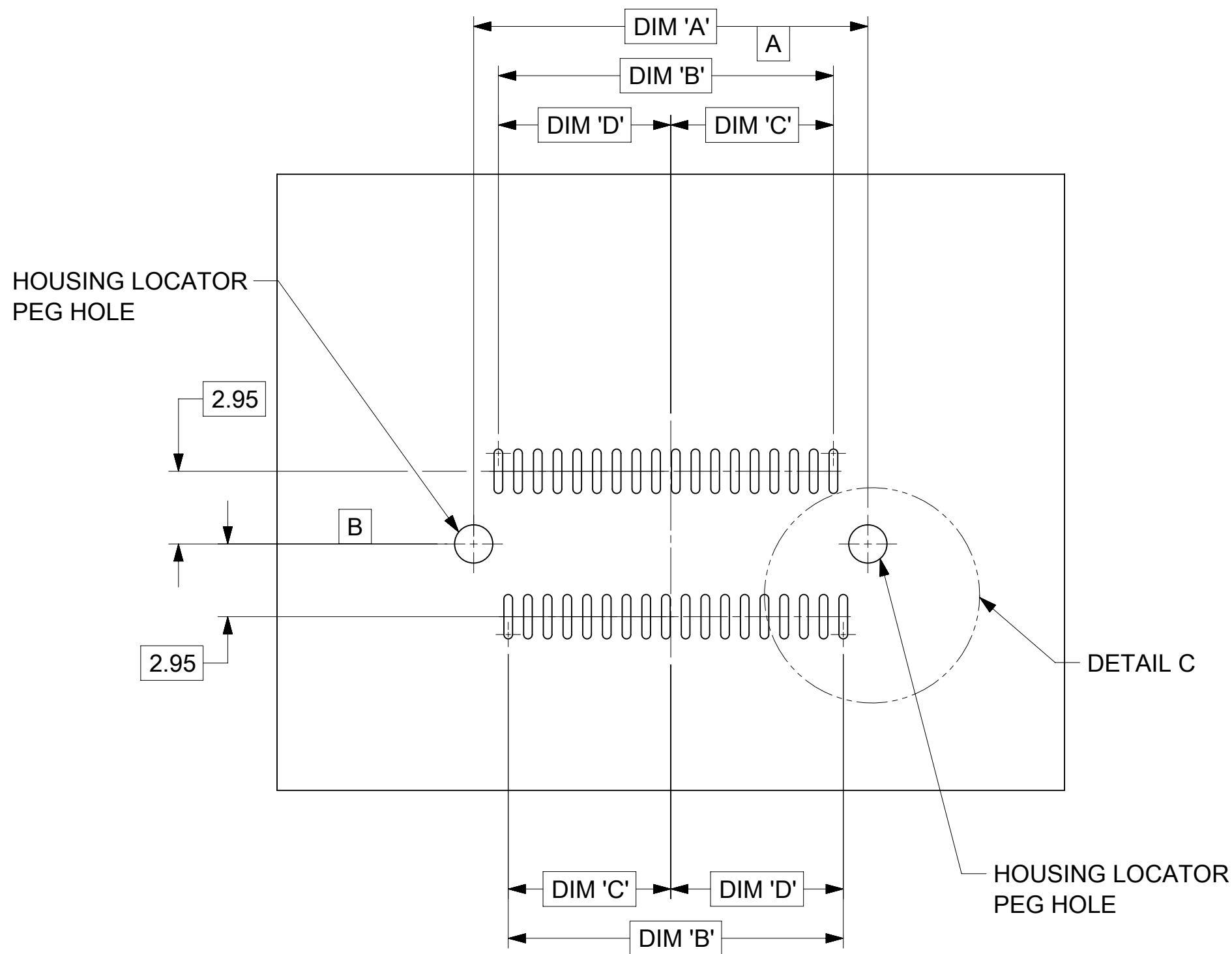
SECTION B-B

CIRCUIT SIZE	MAT'L NUMBER	PLATING OPTION	DIM 'A'	DIM 'B'	DIM 'C'
26	75577-1001	OPTION 1	13.40	11.80	12.00
26	75577-1005	OPTION 2	13.40	11.80	12.00
36	75577-1002	OPTION 1	17.40	15.80	16.00
36	75577-1006	OPTION 2	17.40	15.80	16.00
50	75577-1003	OPTION 1	23.00	21.40	21.60
50	75577-1007	OPTION 2	23.00	21.40	21.60
68	75577-1004	OPTION 1	30.20	28.60	28.80

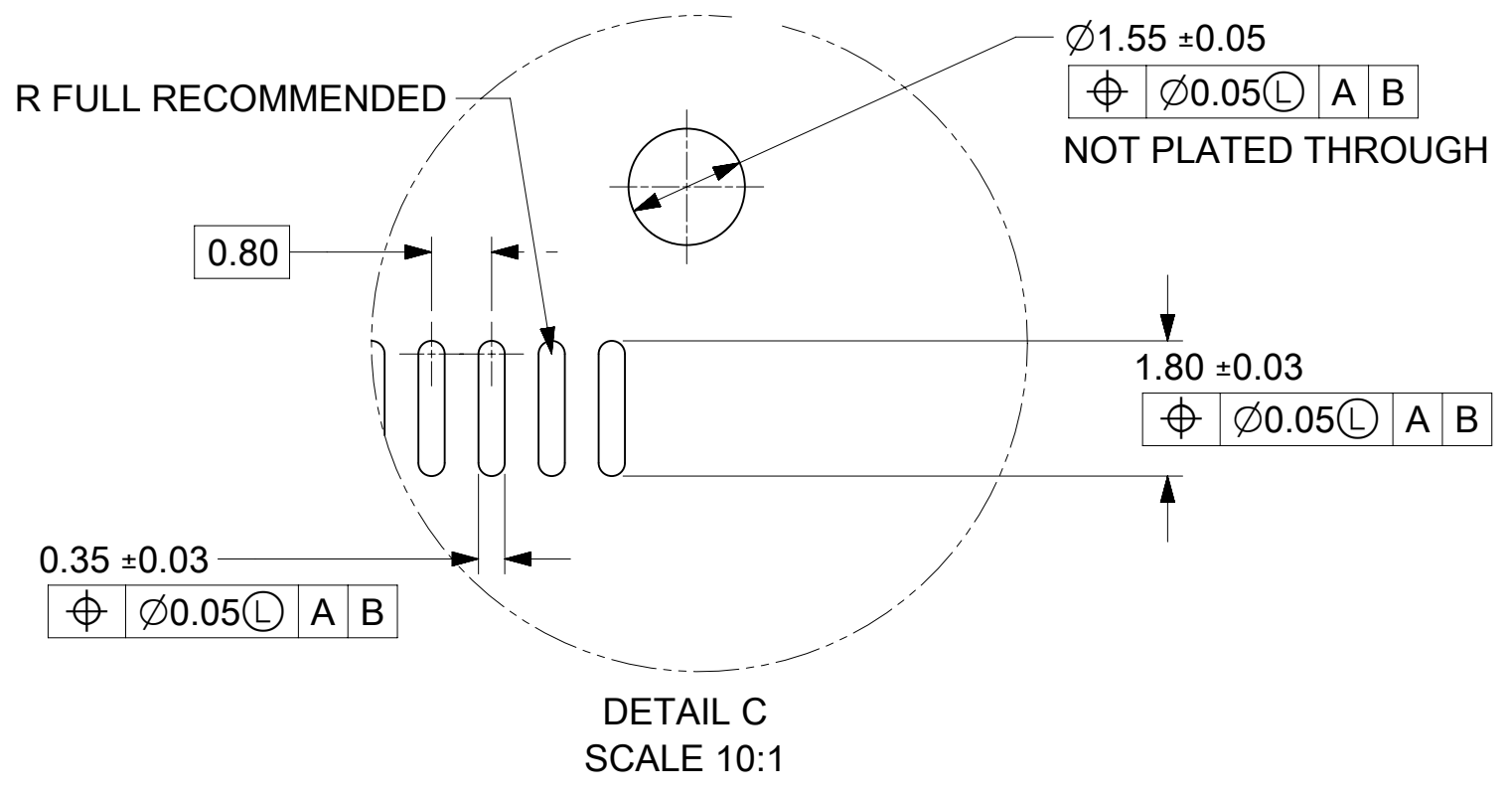


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DIMENSION UNITS mm	SCALE 5:1	CURRENT REV DESC: OBSOLETE PART NUMBER AS PER PCN#510579	molex		
GENERAL TOLERANCES (UNLESS SPECIFIED)		EC NO: 675088			
4 PLACES ±	MM INCH	DRWN: SUGEEB 2021/08/02	PRODUCT CUSTOMER DRAWING		
3 PLACES ±		CHK'D: GGA 2021/09/08	DOCUMENT NUMBER		
2 PLACES ± 0.13		APPR: GGA 2021/09/08	SD-75577-002		
1 PLACE ± 0.25		INITIAL REVISION:	DOC TYPE	DOC PART	REVISION
0 PLACES ±		DRWN: JLSWENSON 06/07/07	PSD	001	E
ANGULAR TOL ± 0.5 °		APPR: MBANAKIS 06/07/07	MATERIAL NUMBER	CUSTOMER	SHEET NUMBER
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIRD ANGLE PROJECTION	DRAWING C-SIZE	75577	GENERAL MARKET	1 OF 2



36 CIRCUIT SHOWN
PATTERN FOR REPRESENTATION ONLY



- NOTES:
1. FOR APPROPRIATE SHELL FOOT PRINT AND KEEP OUT AREAS, SEE SD-76010-002
 2. PAD CONFIGURATION FOR FIRST MATE
 3. PAD CONFIGURATION FOR SECOND MATE
 4. PAD CONFIGURATION FOR THIRD MATE (HIGH SPEED SIGNALS)
 5. FOR PIN ASSIGNMENTS AND MATING SEQUENCE (1ST, 2ND, 3RD), SEE APPLICABLE SPECIFICATION
 6. MINIMUM STEP REQUIRED IF PCB MADE WIDER THAN CARD TONGUE
 7. THESE ARE GENERIC DETAILS THAT DESCRIBES THE CONFIGURATION OF VARIOUS PCB DESIGN ELEMENTS. THE CUSTOMER MUST DETERMINE WHERE AND WHEN TO USE EACH ELEMENT TO ACCOMODATE THEIR SPECIFIC APPLICATION.
 8. CHAMFER ROUGHNESS NOT TO EXCEED 3.17µM.
 9. EDGE CARD CHAMFER NOT TO GO THROUGH GOLD PAD.

CIRCUIT SIZE	PEG TO PEG	FIRST TO LAST PAD	CENTERLINE TO PAD	CENTERLINE TO PAD	MODULE BOARD WIDTH
	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'
26	12.00	9.60	4.60	5.00	11.60
36	16.00	13.60	6.60	7.00	15.60
50	21.60	19.20	9.40	9.80	21.20
68	28.80	26.40	13.00	13.40	28.40

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DIMENSION UNITS	SCALE	CURRENT REV DESC: OBSOLETE PART NUMBER AS PER PCN#510579	molex		
mm	5:1				
GENERAL TOLERANCES (UNLESS SPECIFIED)			SALES DRAWING IPASS VERTICAL CONNECTOR .8 MM PITCH I/O		
	MM	INCH	PRODUCT CUSTOMER DRAWING		
4 PLACES	±	±	DOCUMENT NUMBER		
3 PLACES	±	±	DOC TYPE		
2 PLACES	± 0.13	±	DOC PART		
1 PLACE	± 0.25	±	REVISION		
0 PLACES	±	±	SD-75577-002		
ANGULAR TOL	± 0.5°		PSD 001 E		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIRD ANGLE PROJECTION	DRAWING	SERIES	MATERIAL NUMBER	CUSTOMER
		C-SIZE	75577	SEE TABLE	GENERAL MARKET
					SHEET NUMBER
					2 OF 2